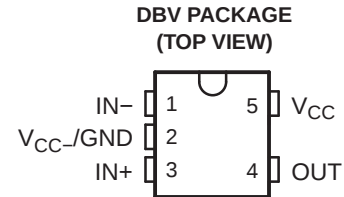


SINGLE DIFFERENTIAL COMPARATOR

Check for Samples: [TL331-Q1](#)

FEATURES

- Qualified for Automotive Applications
- Single Supply or Dual Supplies
- Wide Range of Supply Voltage: 2 V to 36 V
- Low Supply-Current Drain Independent of Supply Voltage: 0.4 mA Typ.
- Low Input Bias Current: 25 nA Typ.
- Low Input Offset Voltage: 2 mV Typ.
- Common-Mode Input Voltage Range Includes Ground
- Differential Input Voltage Range Equal to Maximum-Rated Supply Voltage: ± 36 V
- Low Output Saturation Voltage
- Output Compatible With TTL, MOS, and CMOS



DESCRIPTION/ORDERING INFORMATION

This device consists of a single voltage comparator that is designed to operate from a single power supply over a wide range of voltages. Operation from dual supplies also is possible if the difference between the two supplies is 2 V to 36 V and V_{CC} is at least 1.5 V more positive than the input common-mode voltage. Current drain is independent of the supply voltage. The output can be connected to other open-collector outputs to achieve wired-AND relationships.

ORDERING INFORMATION⁽¹⁾

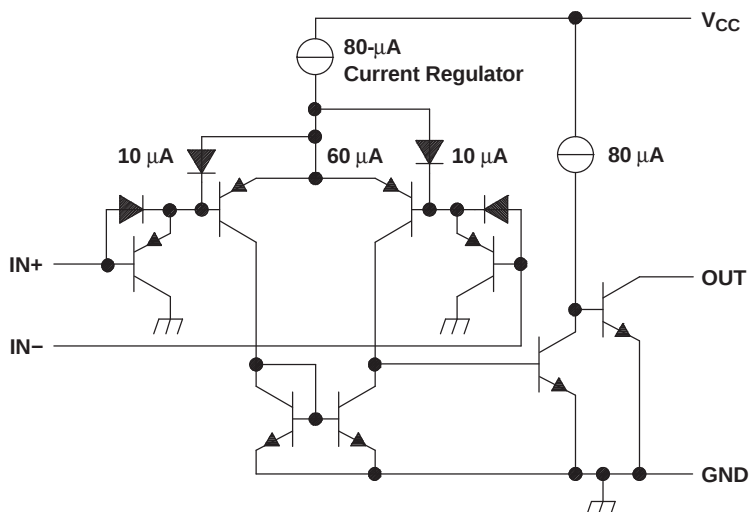
T_A	PACKAGE ⁽²⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	SOT-23 – DBV	Reel of 3000	TL331IDBVRQ1	TQ1U
–40°C to 125°C	SOT-23 – DBV	Reel of 3000	TL331QDBVRQ1	T1RU

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI Web site at www.ti.com.

(2) Package drawings, thermal data, and symbolization are available at www.ti.com/packaging.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

LOGIC DIAGRAM**SCHEMATIC**

COMPONENT COUNT	
Epi-FET	1
Diodes	2
Resistors	1
Transistors	20

Note: Current values shown are nominal.

ABSOLUTE MAXIMUM RATINGS⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

V_{CC}	Supply voltage ⁽²⁾	36 V
V_{ID}	Differential input voltage ⁽³⁾	± 36 V
V_I	Input voltage range (either input)	-0.3 V to 36 V
V_O	Output voltage	36 V
I_O	Output current	20 mA
	Duration of output short-circuit to ground ⁽⁴⁾	Unlimited
θ_{JA}	Package thermal impedance ⁽⁵⁾ ⁽⁶⁾	206°C/W
T_J	Operating virtual junction temperature	150°C
T_{stg}	Storage temperature range	-65°C to 150°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under *recommended operating conditions* is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values, except differential voltages, are with respect to the network ground.
- (3) Differential voltages are at IN+ with respect to IN-.
- (4) Short circuits from outputs to V_{CC} can cause excessive heating and eventual destruction.
- (5) Maximum power dissipation is a function of $T_J(\text{max})$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\text{max}) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
- (6) The package thermal impedance is calculated in accordance with JESD 51-7.

ELECTRICAL CHARACTERISTICS

at specified free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS ⁽¹⁾	T_A	MIN	TYP	MAX	UNIT
V_{IO} Input offset voltage	$V_{CC} = 5\text{ V to } 30\text{ V}$, $V_O = 1.4\text{ V}$, $V_{IC} = V_{IC(min)}$	25°C		2	5	mV
		–40°C to 125°C			9	
I_{IO} Input offset current	$V_O = 1.4\text{ V}$	25°C		5	50	nA
		–40°C to 125°C			250	
I_{IB} Input bias current	$V_O = 1.4\text{ V}$	25°C		–25	–250	nA
		–40°C to 125°C			–400	
V_{ICR} Common-mode input voltage range ⁽²⁾		25°C		0 to $V_{CC} - 1.5$		V
		–40°C to 125°C		0 to $V_{CC} - 2$		
A_{VD} Large-signal differential voltage amplification	$V_{CC} = 15\text{ V}$, $V_O = 1.4\text{ V to } 11.4\text{ V}$, $R_L \geq 15\text{ k}\Omega$ to V_{CC}	25°C		50	200	V/mV
I_{OH} High-level output current	$V_{OH} = 5\text{ V}$, $V_{ID} = 1\text{ V}$	25°C		0.1	50	nA
	$V_{OH} = 30\text{ V}$, $V_{ID} = 1\text{ V}$	–40°C to 125°C			1	μA
V_{OL} Low-level output voltage	$I_{OL} = 4\text{ mA}$, $V_{ID} = -1\text{ V}$	25°C		150	400	mV
		–40°C to 125°C			700	
I_{OL} Low-level output current	$V_{OL} = 1.5\text{ V}$, $V_{ID} = 1\text{ V}$	25°C		6		mA
I_{CC} Supply current	$R_L = \infty$, $V_{CC} = 5\text{ V}$	25°C		0.4	0.7	mA

(1) All characteristics are measured with zero common-mode input voltage, unless otherwise specified.

(2) The voltage at either input or common-mode should not be allowed to go negative by more than 0.3 V. The upper end of the common-mode voltage range is $V_{CC} + 1.5\text{ V}$, but either or both inputs can go to 30 V without damage.

SWITCHING CHARACTERISTICS

 $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	TYP	UNIT
Response time	R_L connected to 5 V through 5.1 k Ω , $C_L = 15\text{ pF}$ ^{(1) (2)}	100-mV input step with 5-mV overdrive	1.3
		TTL-level input step	0.3

(1) C_L includes probe and jig capacitance.

(2) The response time specified is the interval between the input step function and the instant when the output crosses 1.4 V.

REVISION HISTORY

Changes from Revision A (July 2010) to Revision B	Page
• Changed V_{ICR} in the Electrical Characteristics	3

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
TL331IDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	
TL331QDBVRQ1	ACTIVE	SOT-23	DBV	5	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

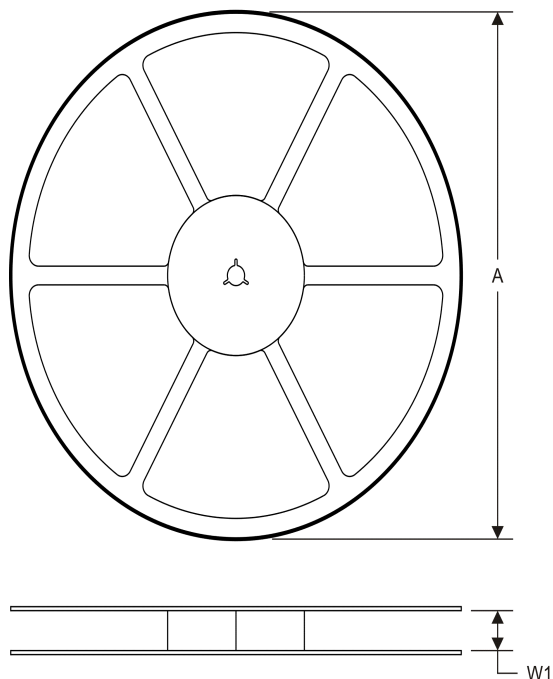
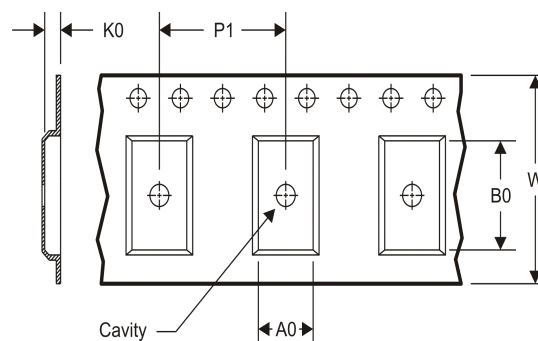
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

OTHER QUALIFIED VERSIONS OF TL331-Q1 :

- Catalog: [TL331](#)

NOTE: Qualified Version Definitions:

-
- Catalog - TI's standard catalog product

TAPE AND REEL INFORMATION
REEL DIMENSIONS

TAPE DIMENSIONS


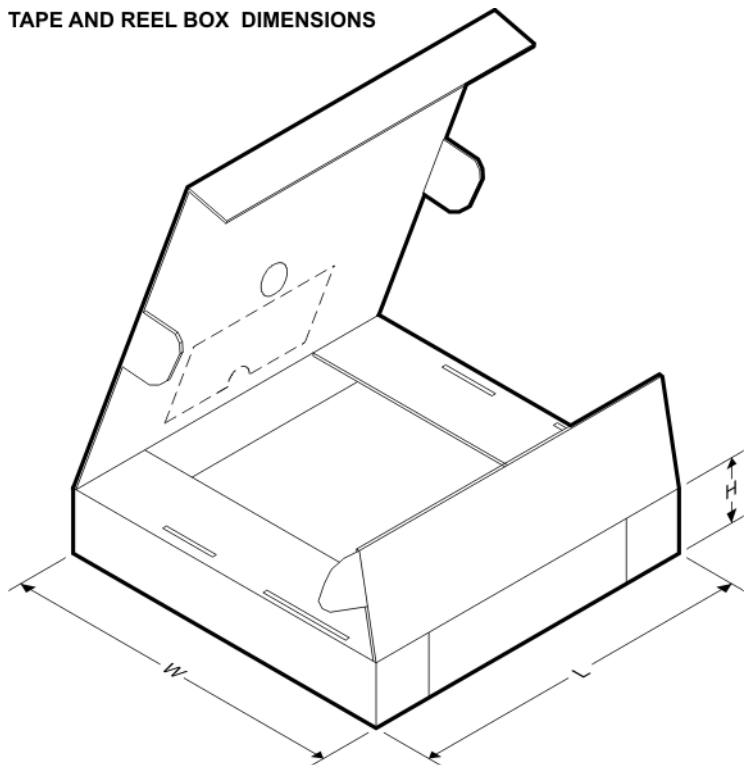
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL331IDBVRQ1	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3
TL331QDBVRQ1	SOT-23	DBV	5	3000	179.0	8.4	3.2	3.2	1.4	4.0	8.0	Q3

TAPE AND REEL BOX DIMENSIONS

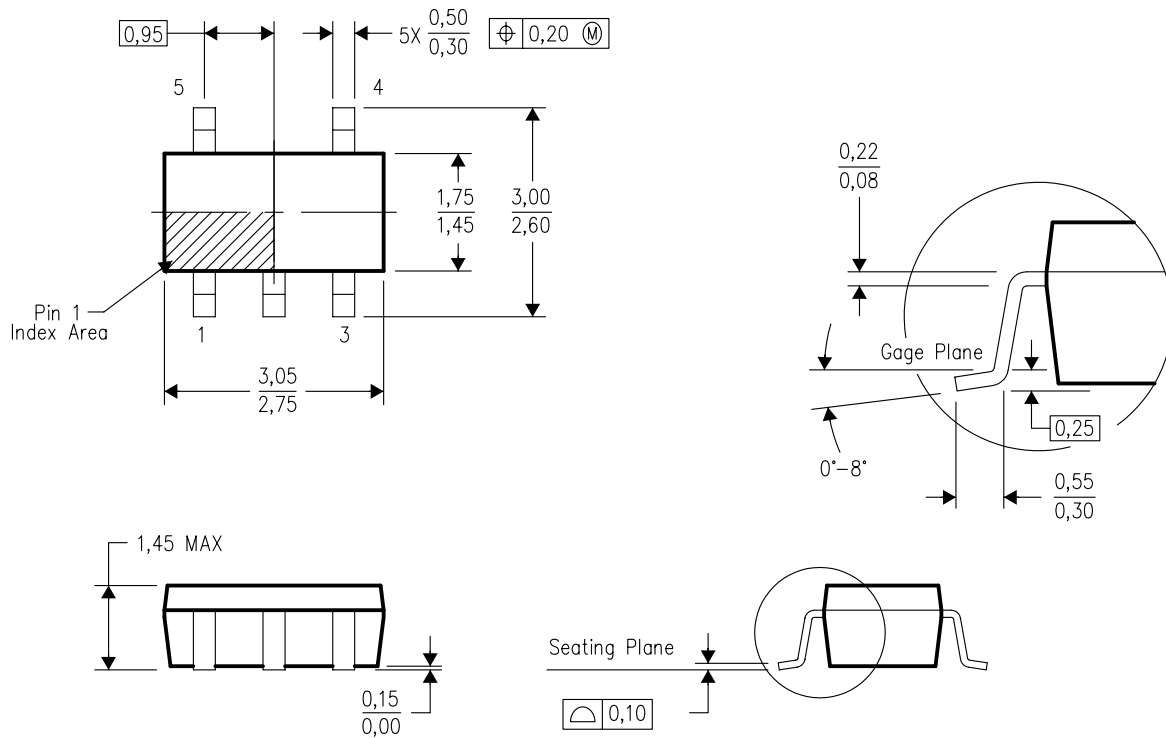


*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL331IDBVRQ1	SOT-23	DBV	5	3000	203.0	203.0	35.0
TL331QDBVRQ1	SOT-23	DBV	5	3000	203.0	203.0	35.0

DBV (R-PDSO-G5)

PLASTIC SMALL-OUTLINE PACKAGE

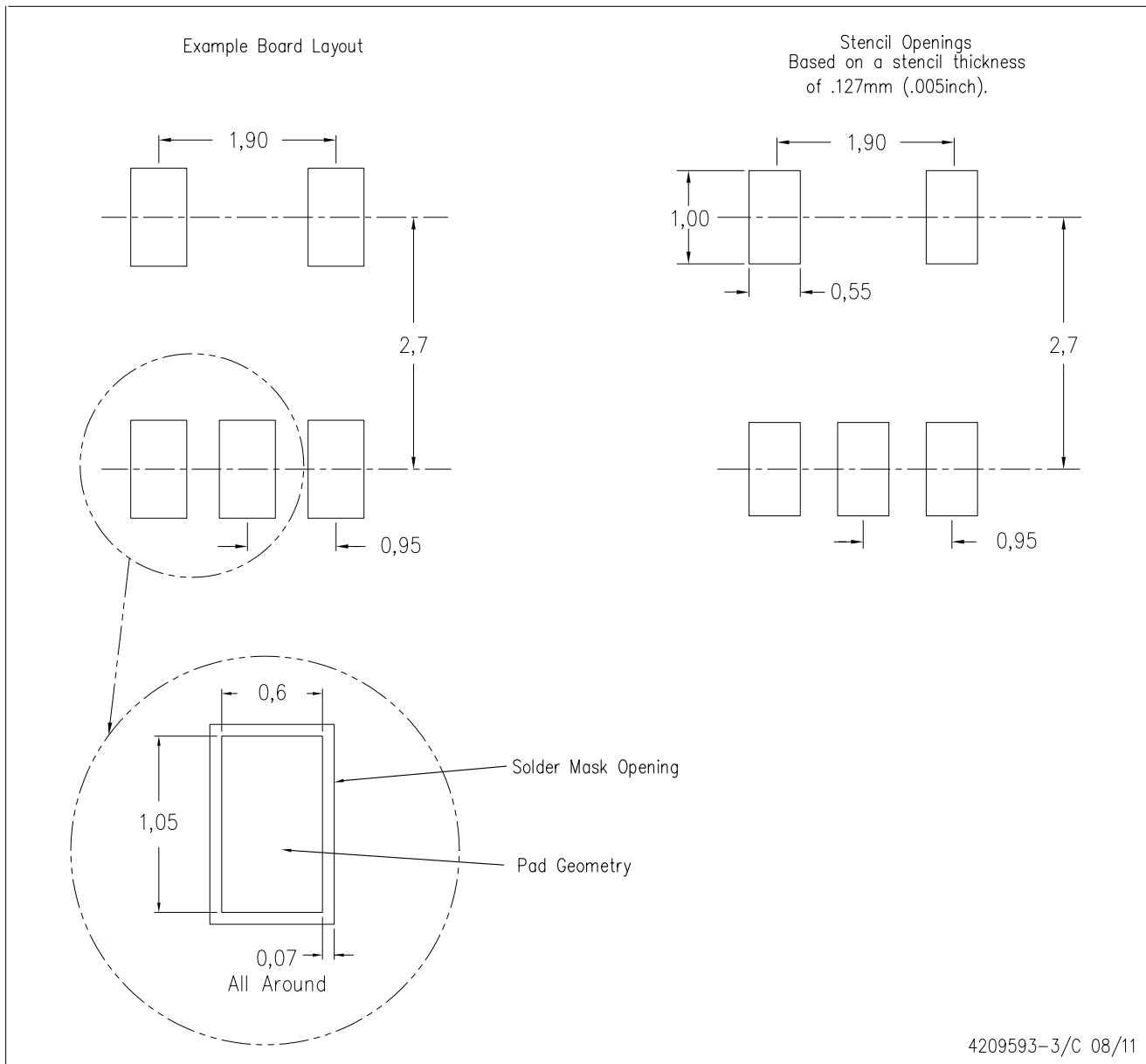


4073253-4/K 03/2006

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion. Mold flash and protrusion shall not exceed 0.15 per side.
 - D. Falls within JEDEC MO-178 Variation AA.

DBV (R-PDSO-G5)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as "components") are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI's terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers' products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers' products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI's goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or "enhanced plastic" are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have **not** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products

Audio	www.ti.com/audio
Amplifiers	amplifier.ti.com
Data Converters	dataconverter.ti.com
DLP® Products	www.dlp.com
DSP	dsp.ti.com
Clocks and Timers	www.ti.com/clocks
Interface	interface.ti.com
Logic	logic.ti.com
Power Mgmt	power.ti.com
Microcontrollers	microcontroller.ti.com
RFID	www.ti-rfid.com
OMAP Applications Processors	www.ti.com/omap
Wireless Connectivity	www.ti.com/wirelessconnectivity

Applications

Automotive and Transportation	www.ti.com/automotive
Communications and Telecom	www.ti.com/communications
Computers and Peripherals	www.ti.com/computers
Consumer Electronics	www.ti.com/consumer-apps
Energy and Lighting	www.ti.com/energy
Industrial	www.ti.com/industrial
Medical	www.ti.com/medical
Security	www.ti.com/security
Space, Avionics and Defense	www.ti.com/space-avionics-defense
Video and Imaging	www.ti.com/video

TI E2E Community

e2e.ti.com